

IN THE CLAIMS:

1. (Currently Amended) A method of testing ~~a circuit on a substrate~~ circuits on substrates, comprising:

- locating the substrates_u in a transfer apparatus;
- moving a surface of a test chuck into contact with the substrates_u held by the transfer apparatus;
- securing the substrates_u to the test chuck;
- moving substantially simultaneously the substrates_u off the transfer apparatus;
- recording an image of a surface of each of the substrates_u;
- moving terminals on the substrates_u into contact with contacts to electrically connect the circuit through terminals and the contacts to a tester, no more than a single image of the surface having been recorded;
- relaying signals through the terminals and the contacts between the electric tester and the circuits;
- disengaging the terminals from the contacts; and
- removing the substrates_u from the test chuck.

2. (Currently Amended) The method of claim 1 wherein the transfer apparatus is a transfer chuck and the image is recorded before having moved the substrates_u off the transfer chuck.

3. (Currently Amended) The method of claim 2 wherein the image is recorded while moving the substrates_u off the transfer chuck.

4. (Original) The method of claim 1 wherein the transfer apparatus is a transfer chuck

and a plurality of separate substrates are located in the transfer chuck, a respective surface of the test chuck is moved into contact with each substrate, each substrate is secured to the test chuck, the substrates move simultaneously off the transfer chuck, and the substrates move simultaneously past the image recordation device so that an image of a surface of each substrate is recorded, each substrate having been moved once only past the image recordation device before the contacts contact terminals on the respective substrate.

5. (Original) The method of claim 4 wherein the images are recorded before having moved the substrates off the transfer chuck.

6. (Original) The method of claim 5 wherein the images are recorded while moving the substrates off the transfer chuck.

7. (Original) The method of claim 4 wherein the image recordation device is a line scanner having a lens which focuses on the surfaces of the substrates.

8. (Currently Amended) The method of claim 1, further comprising:
moving the test chuck so that the substrates move[[s]] past an image recordation device to record the image of the surface of each substrate once only before moving the terminals into contact with the contacts.

9. (Currently Amended) A method of testing a circuit on a plurality of separate substrates, comprising:
locating the substrates in respective slots in a transfer chuck;
moving a plurality of respective surfaces of a test chuck into contact with each

respective substrate held by the transfer chuck;

securing the substrates to the test chuck;

moving the test chuck relative to the transfer chuck so that the substrates move off the transfer chuck;

moving the test ~~handler~~ chuck so that the substrates move past an image recordation device having at least one lens focusing on a line across a width, transverse to a direction in which the substrates move, of each substrate, to record an image of a surface of each substrate;

moving terminals on the substrates into contact with contacts to electrically connect a circuit on each substrate through the terminals and the contacts to an electric tester, each substrate having been moved once only past the image recordation device to record the image of the surface of the respective substrate;

relaying signals through the terminals and the contacts between the electric tester and the respective circuits;

disengaging the terminals from the contacts; and

removing the substrates from the test chuck ~~handler~~.